


## Full Material Declaration for attached parts list

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	<p><b>Diotec Semiconductor AG</b>  DUNS number: 330866844  -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany  Declarations authorised by  Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2014 [Approved: 07 February 2025 14:05 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.23%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.464%
			GOLD, ELEMENTAL	7440-57-5	0.611%
			ALUMINUM, ELEMENTAL	7429-90-5	0.66%
			Tin elemental	7440-31-5	3.672%
			Elemental silicon	7440-21-3	94.593%
			Carbon black	1333-86-4	1%
Encapsulation	EP (Epoxy resin)	53.656%	Phenol, polymer with formaldehyde	9003-35-4	5%
			ZINC BORATE	1332-07-6	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
Inner preparation	Copper alloys	0.004%	Quartz sand	60676-86-0	79%
Leadfinish	Tin plating	13.32%	COPPER, ELEMENTAL	7440-50-8	100%
			Tin elemental	7440-31-5	100%
Leadframe	Steel and iron materials	32.79%	SILVER, ELEMENTAL	7440-22-4	4.5%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	40.34%
			Elemental iron	7439-89-6	55.16%

## Attached parts list

Part number	Part name
SOT-23/TO-236_Pb&H-free_(EB)_sin	Diode / Transistor SMD